

CLAIMS

1. A ceramic substrate provided with a conductor layer on the surface of said ceramic substrate or inside said ceramic substrate,
5 wherein: the ratio (t_2/t_1) of the average thickness of said conductor layer (t_2) to the average thickness of said ceramic substrate (t_1) is less than 0.1; and a dispersion of the thickness of the conductor layer to the average thickness of the conductor layer is in a range of -70 to +150%.
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2. The ceramic substrate according to claim 1, wherein said ceramic substrate is in a disc-shape with a diameter exceeding 150 mm.
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3. The ceramic substrate according to claim 1 or 2, wherein the thickness of said ceramic substrate is 25 mm or less.
- 20 4. The ceramic substrate according to any of claims 1 to 3, wherein said conductor layer is an electrostatic electrode.
- 25 5. The ceramic substrate according to any of claims 1 to 3, wherein said conductor layer is a resistance heating element.
6. The ceramic substrate according to any of claims 1 to 3, wherein said conductor layer is any of a chuck top electrode, a guard electrode and a ground electrode.
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